Ultra-Low Voltage Buffer

The NL17SV16XV5T2 is an ultra–high performance single Buffer fabricated in sub–micron silicon gate (0.35 μ) CMOS technology with excellent performance down to 0.9 V. This device is ideal for extremely high–speed and high–drive applications. Additionally, limitations of board space are no longer a constraint. The very small SOT–553 makes this device fit most tight designs and spaces.

The internal circuit is composed of three stages; including a buffered output which provides high noise immunity and stable output. The NL17SV16XV5T2 input structure provides protection when voltages up to 3.6 V are applied.

Features

- Extremely High Speed: 1.5 ns (Typ) at $V_{CC} = 3.3 \text{ V}$
- Designed for 0.9 V to 3.6 V Operation
- Overvoltage Tolerance (OVT)* Input Permits Logic Translation
- Balanced ±24 mA Output Drive @ 3.3 Volts
- Near Zero Static Supply Current
- Ultra-Tiny SOT-553 5 Pin Package Only 1.6 x 1.6 mm Footprint
- Ultra-Tiny SOT-553 5-Pin Package, only 1.6 x 1.6 x 0.6 mm
- These are Pb-Free Devices

Typical Applications

- Cellular
- Digital Camera
- PDA
- Digital Video

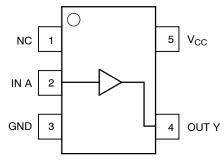


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



ON Semiconductor®

http://onsemi.com

MARKING

DIAGRAM



UN

SOT-553 XV5 SUFFIX CASE 463B

UN

М

Device CodeDate Code*

A = Assembly Location

Y = Year
W = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT						
1	NC					
2	IN A					
3	GND					
4	OUT Y					
5	V _{CC}					

FUNCTION TABLE

Input A	Output Y
L	L
н	Н

ORDERING INFORMATION

Device	Package	Shipping†
NL17SV16XV5T2	SOT-553*	4000 / Tape & Reel
NL17SV16XV5T2G	SOT-553*	4000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}Overvoltage Tolerance (OVT) enables input pins to function outside (higher) of their operating voltages, with no damage to the devices or to signal integrity.

^{*}This package is inherently Pb-Free.

MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to + 4.6	V
VI	DC Input Voltage	-0.5 to + 4.6	V
Vo	DC Output Voltage	-0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current V _I < GND	±50	mA
I _{OK}	DC Output Diode Current $V_O = GND$ $V_O = V_{CC}$	-50 +50	mA
Io	DC Output Sink Current	±50	mA
I _{CC}	DC Supply Current per Supply Pin	±50	mA
I _{GND}	DC Ground Current per Ground Pin	±50	mA
T _{STG}	Storage Temperature Range	– 65 to +150	°C
T_L	Lead Temperature, 1.0 mm from Case for 10 seconds	260	°C
TJ	Junction Temperature Under Bias	+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 1)	250	°C/W
P_{D}	Power Dissipation in Still Air at 85°C	250	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen index: 28 to 34	UL 94 V-0 @ 0125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3)	2000 300	V

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
- Tested to EIA/JESD22-A114-A.
 Tested to EIA/JESD22-A115-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V _{IN}	Digital Input Voltage	0	3.6	V	
V _{out}	Output Voltage		0	V _{CC}	V
I _{OH} /I _{OL}	Output Current	$\begin{array}{c} \text{V}_{CC} = 3.0 \text{ V to } 3.6 \text{ V} \\ \text{V}_{CC} = 2.3 \text{ V to } 2.7 \text{ V} \\ \text{V}_{CC} = 1.65 \text{ V to } 1.95 \text{ V} \\ \text{V}_{CC} = 1.4 \text{ V to } 1.6 \text{ V} \\ \text{V}_{CC} = 1.1 \text{ V to } 1.3 \text{ V} \\ \text{V}_{CC} = 0.9 \text{ V} \end{array}$		±24 ±18 ±6 ±4 ±2 ±0.1	mA
t _A	Operating Temperature Range. All Package Ty	-40	+85	°C	
t _r , t _f	Input Rise or Fall Time	$V_{CC} = 3.3V \pm 0.3 V$	0	10	nS/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

DC CHARACTERISTICS- Digital Section (Voltages Referenced to GND)

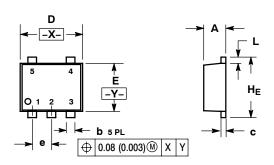
				T _A = 25°C		T _A = −40 to 85°C		
Symbol	Parameter	Condition	V _{cc}	Min	Max	Min	Max	Unit
V _{IH}	High Level		0.90	0.65 x V _{CC}		0.65 x V _{CC}		V
	Input Voltage		$1.10 \le = V_{CC} \le 1.30$	0.65 x V _{CC}		0.65 x V _{CC}		
			$1.40 \le V_{CC} \le 1.60$	0.65 x V _{CC}		0.65 x V _{CC}		
			$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$	0.65 x V _{CC} 1.6		0.65 x V _{CC} 1.6		
			$2.30 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$	2.0		2.0		
V _{IL}	Low Level		0.90		0.35 x V _{CC}		0.35 x V _{CC}	V
· IL	Input Voltage		$1.10 \le V_{CC} \le 1.30$		0.35 x V _{CC}		0.35 x V _{CC}	•
			$1.40 \le V_{CC} \le 1.60$		0.35 x V _{CC}		0.35 x V _{CC}	
			$1.65 \le V_{CC} \le 1.95$		0.35 x V _{CC}		0.35 x V _{CC}	
			$2.30 \le V_{CC} \le 2.70$		0.7		0.7	
			$2.70 \le V_{CC} \le 3.60$		0.8		0.8	
V_{OH}	High Level	I _{OH} = -100 μA	0.90	V _{CC} - 0.1		V _{CC} - 0.1		V
	Output Voltage		$1.10 \le V_{CC} \le 1.30$	V _{CC} - 0.1		V _{CC} - 0.1		
			$1.40 \le V_{CC} \le 1.60$ $1.65 \le V_{CC} \le 1.95$	V _{CC} - 0.2 V _{CC} - 0.2		V _{CC} - 0.2 V _{CC} - 0.2		
			$2.30 \le V_{CC} \le 1.93$ $2.30 \le V_{CC} \le 2.70$	$V_{CC} = 0.2$ $V_{CC} = 0.2$		V _{CC} - 0.2 V _{CC} - 0.2		
			$2.70 \le V_{CC} \le 3.60$	V _{CC} - 0.2		V _{CC} - 0.2		
		I _{OH} = -2.0 mA	$1.10 \le V_{CC} \le 1.30$	0.75 x V _{CC}		0.75 x V _{CC}		
		I _{OH} = -4.0 mA	$1.40 \le V_{CC} \le 1.60$	0.75 x V _{CC}		0.75 x V _{CC}		
		I _{OH} = -6.0 mA	$1.65 \le V_{CC} \le 1.95$	1.25		1.25		
			$2.30 \le V_{CC} \le 2.70$	2.0		2.0		
		I _{OH} = -12 mA	$2.30 \le V_{CC} \le 2.70$	1.8		1.8		
			$2.70\leqV_{CC}\leq3.60$	2.2		2.2		
		I _{OH} = -18 mA	$2.30 \le V_{CC} \le 2.70$	1.7		1.7		
			$2.70 \le V_{CC} \le 3.60$	2.4		2.4		
		$I_{OH} = -24 \text{ mA}$	$2.70 \leq V_{CC} \leq 3.60$	2.2		2.2		
V_{OL}	Low Level	I _{OL} = 100 μA	0.90		0.1		0.1	٧
	Output Voltage		$1.10 \le V_{CC} \le 1.30$		0.1		0.1	
			$1.40 \le V_{CC} \le 1.60$		0.2		0.2	
			$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$		0.2 0.2		0.2 0.2	
			$2.70 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$		0.2		0.2	
		I _{OL} = 2.0 mA	$1.10 \le V_{CC} \le 1.30$		0.25 x V _{CC}		0.25 x V _{CC}	
		I _{OL} = 4.0 mA	$1.40 \le V_{CC} \le 1.60$		0.25 x V _{CC}		0.25 x V _{CC}	
		I _{OL} = 6.0 mA	$1.65 \le V_{CC} \le 1.95$		0.3		0.3	
		I _{OL} = 12 mA	$2.30 \le V_{CC} \le 2.70$		0.4		0.4	
		10L = 12 11,7 1	$2.70 \le V_{CC} \le 3.60$		0.4		0.4	
		I _{OL} = 18 mA	$2.30 \le V_{CC} \le 2.70$		0.6		0.6	
			$2.70 \le V_{CC} \le 3.60$		0.4		0.4	
		I _{OL} = 24 mA	$2.70 \le V_{CC} \le 3.60$		0.55		0.55	
I _{IN}	Input Leakage Current	0 = V _I = 3.6 V	0.90 to 3.60		±0.1		±0.9	μΑ
I _{OFF}	Power Off Leakage Current		0		1		5	μΑ
I _{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND	0.90 to 3.60		0.9		5	μΑ

AC CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

		-40°C			25°C		85	°C	
Symbol	Parameter	Condition	V _{CC}	Min	Тур	Max	Min	Max	Unit
T _{PHL,}	Propagation Delay	C_L = 15 pF, R_L = 1.0 M Ω	0.90		20				nS
T _{PLH}		C_L = 15 pF, R_L = 2.0 k Ω	$1.10 \le V_{CC} \le 1.30$ $1.40 \le V_{CC} \le 1.60$	2.0 1.0	6.0 3.2	13 6.1	1.0 1.0	16.9 7.0	nS
		C_L = 30 pF, R_L = 500 k Ω	$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$	1.0 0.8 0.7	2.0 1.2 1.0	5.2 3.7 3.3	1.0 0.7 0.6	6.2 4.4 3.8	nS
C _{IN}	Input Capacitance		0		2.0				pF
C _{OUT}	Output Capacitance		0		4.5				pF
C _{PD}	Power Dissipation Capacitance	V _I = 0 V or V _{CC} F = 10 MHz	0.90 to 3.60		20				pF

PACKAGE DIMENSIONS

SOT-553, 5 LEAD CASE 463B-01 ISSUE B

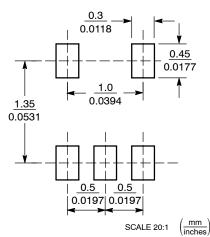


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS				INCHES			
DIM	MIN	NOM	MAX	MIN	MIN NOM			
Α	0.50	0.55	0.60	0.020	0.022	0.024		
b	0.17	0.22	0.27	0.007	0.009	0.011		
С	0.08	0.13	0.18	0.003	0.005	0.007		
D	1.50	1.60	1.70	0.059	0.063	0.067		
E	1.10	1.20	1.30	0.043	0.047	0.051		
е		0.50 BSC		0.020 BSC				
L	0.10	0.20	0.30	0.004	0.008	0.012		
HE	1.50	1.60	1.70	0.059	0.063	0.067		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and was registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.

NL17SV16XV5T2/D